

ABSTRACT OF THE DISCLOSURE

SOLDERABLE INJECTION-MOLDED INTEGRATED CIRCUIT SUBSTRATE AND METHOD THEREFOR

5 A solderable injection-molded integrated circuit substrate provides a mounting and interconnect structure for integrated circuits. Circuit traces within channels on the substrate provide interconnects that are isolated by the channel sides and solderable mounting contacts for Ball Grid Array (BGA) or wire-
10 bondable integrated circuit dies. The substrate is injection-molded and then electroplated or seed plated and an etchant-resistive material is applied. The substrate is exposed to an etchant, removing the plated material from undesired locations and leaving the plated material in contact areas and trace areas
15 within the channels. An integrated circuit die is then wire-bonded or solder ball attached to the substrate.